

# MLC MicroSD Card 3.0

**PHANES-F Series** 

**Document No.:** 100-xPMSD-PFISM

Version No.: 05V0

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# **Product Features**

#### ■ Flash IC

- Samsung 14nm NAND Flash IC.
- Multi-Level Cell (MLC) technology

#### ■ Compatibility

- SD Memory Card Specifications, Part 1 Physical Layer
   Specification, version 3.1 Final
- SD Memory Card Specifications, Part 3, Security
   Specification, Version 3.0 Final

#### ■ Additional Capabilities

- S.M.A.R.T.\*<sup>1</sup> (Self-Monitoring, Analysis and Reporting Technology) feature set support.
- Supports SD command Class 2/4/6/10
- Supports UHS-1
- Supports SD mode and SPI mode
- Supports CPRM
- Supports Embedded Mode
- Support bad Block Management
- Support both Static and Dynamic Wear Leveling

#### ■ Mechanical

- 8 exposed contact pins on one side.
- Dimension: 15.0mm x 11.0mm x 1.0mm.
- Weight: 0.3 g / 0.01 oz.

#### ■ Power Operating Voltage 3.3V(+/-) 10%

- Read Mode: 400 mA (max.)

- Write Mode: 400 mA (max.)

- Standby Mode: 1000 uA (max.)

# Performance (Maximum value) \*2 microSDHC card performance

- Sequential Read: 95.0 MB/sec. (max.)

Sequential Write: 62.0 MB/sec. (max.)
 micro SDXC card performance

- Sequential Read: 94.3 MB/sec. (max.)

- Sequential Write: 76.7 MB/sec. (max.)

#### ■ Capacity

- 8GB, 16GB, 32GB

#### ■ Reliability

ECC: Designed with BCH 42-bit/1KB ECC
 Algorithm.

- **MTBF:** > 3,000,000 hours

- **Temperature:** (Operating)

Wide Temp. Grade:  $-40^{\circ}$ C  $\sim +85^{\circ}$ C

Vibration: 80Hz~2000Hz/20G.

Shock: 0.5ms, 1500 G, 3 axes.

- Erase counts: 3K

#### ■ Certifications and Declarations

- **Certifications**: CE & FCC

- **Declarations**: RoHS & REACH

#### Remarks:

- 1. Support official S.M.A.R.T. Utility.
- 2. Sequential performance is based on
   CrystalDiskMark 5.1.2 with file size 1000MB



# **Order Information**

#### I. Part Number List

♦ APRO MLC Micro Secure Digital Memory Card PHANES-F Series

Product Picture	Grade	Wide Temp Grade ( -40°C ~ +85°C )				
	8GB	WPMSD008G-PFISM				
APRO Co., Ltd.	16GB	WPMSD016G-PFISM				
MLC Micro	32GB	WPMSD032G-PFISM				

II. Part Number Decoder:

X1 X2 X3 X4 X5 X6 X7 X8 X9 - X11 X12 X13 X14 X15 X16

X1 : Grade

**W:** Wide Temp Grade- operating temp. -40° C  $\sim$  +85 ° C

X2: The material of case

P: Plastic casing

X3 X4 X5 : Product category

MSD: Micro Secure Digital (SD) memory card

X6 X7 X8 X9 : Capacity

**008G:** 8GB **032G:** 32GB

**016G:** 16GB

X11 : Controller

P: PHANES Series

X12 : Controller version

A, B, C.....

X13 : Controller Grade

 ${f I}$ : Industrial grade

X14 : Flash IC

S: Samsung NAND Flash IC

X15 : Flash IC grade / Type

M: Samsung 14nm MLC Flash IC



# **Revision History**

Revision	Description	Date		
1.0	Initial release	2015/06/12		
2.0	Flash IC upgrade to 15nm	2016/03/21		
2.1	Add 128GB microSDXC capacity	2017/5/18		
2.2	Updated Document form	2019/06/17		
2.3	Updated Document form	2020/05/18		
2.0	Remove 128GB microSDXC capacity	2024/04/24		
3.0	Add. Samsung MLC Flash IC Solution	2021/04/01		
	Correct description:			
	Supply Voltage: 3.3V(+/-) 10%	2021/07/9		
3.1	to			
	Supply Voltage: 2.7V to 3.6V			
3.2	Add. TBW	2022/04/01		
4.0	Remove Kioxia solution	2022/12/22		
5.0	- <b>ECC:</b> Designed with BCH 42-bit/1KB ECC Algorithm.	2024/10/21		



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#### 1. Introduction

APRO MLC Micro Secure Digital Memory Card PHANES-F Series is specifically designed to meet the security, performance and environmental requirements of some significant applications such like networking, telecommunications and data-communications, mobile & embedded computing, medical instruments and industrial computing applications.

The main used Flash memory is MLC-NAND Type Flash memory chips are 8GB, 16GB and 32GB. APRO MLC Micro SD Cards include a copyright protection that complies with the security of the SDMI standard, and the physical form-factor, pin assignment.

#### 1.1. *Scope*

This document describes the key features and specifications of APRO MLC Micro Secure Digital Memory Cards.

### 1.2. Flash Management Technology - Static & Dynamic Wear Leveling

NAND flash devices can only undergo a limited number of program/erase cycles, and in most cases, the flash media are not used evenly. If some areas get updated more frequently than others, the lifetime of the device would be reduced significantly. Thus, Wear Leveling is applied to extend the lifespan of NAND Flash by evenly distributing write and erase cycles across the media.

APRO MLC Micro Secure Digital Memory Card PHANES-F Series provides advanced Wear Leveling algorithm, which can efficiently spread out the flash usage through the whole flash media area. Moreover, by implementing both dynamic and static Wear Leveling algorithms, the life expectancy of the NAND flash is greatly improved.

## 1.3. Bad Block Management

#### > Early Bad Block

The fault block generated during the manufacturing process of NAND Flash is called Early Bad Block.

#### Later Bad Block

In the process of use, as the number of operations of writing and erasing increases, a fault block is gradually generated, which is called a Latter Bad Block.

**Bad block management** is a management mechanism for a bad block to be detected by the control IC and mark bad blocks in the NAND Flash and improve the reliability of data access. The bad block management mechanism of the control IC will establish a **Bad Block Table** when the NAND Flash is started for the first time, and will also record the errors found in the process of use in the bad block table, and data is ported to new valid blocks to avoid data loss.

In order to detect the initial bad blocks to handle run time bad blocks, APRO MLC Micro Secure Digital Memory Card PHANES-F Series provides the **Bad Block Management** scheme. It remaps a bad block to one of the reserved blocks so that the data contained in one bad block is not lost and new data writes on a bad block is avoided.

#### 1.4. Embedded Mode

Embedded mode is a function specially designed for operating systems that do not utilize FAT. Often under non Windows OS, for example Linux or customized host, wear leveling mechanism of APRO MLC MicroSD cards will be affected or even disabled in some cases. With embedded mode activated, MLC MicroSD cards ensure that under any circumstances, wear leveling mechanism can operate normally to keep the usage of blocks even throughout the MicroSD card's life cycle. This is especially a great add-on for security cameras or drive recorders.



## 2. Product Specifications

For all the following specifications, values are defined at ambient temperature and nominal supply voltage unless otherwise stated.

# 2.1. System Environmental Specifications

Table 1: Environmental Specification

APRO Micro Secure Digital Memory Card		Wide temp Grade			
PHANES-F Series		WPMSDXXXG-PFISM			
	Operating:	-40°C ~ +85°C			
Temperature	Non-operating:	-50°C ~ +95°C			
Humidity	Operating & Non-operating:	10% ~ 95% non-condensing			
Vibration	Operating & Non-operating:	80Hz~2000Hz/20G.			
Shock	Operating & Non-operating:	0.5ms, 1500 G, 3 axes			

# 2.2. System Power Requirements

Table 2: Power Requirement

APRO Micro Secure Digi	tal Memory Card	Wide temp Grade		
PHANES-F Series		WPMSDXXXG-PFISM		
DC Input Voltage (VCC)		2.7V to 3.6V		
Maximum average value	Reading Mode :	400 mA (max.)		
	Writing Mode:	400 mA (max.)		
	Standby Mode :	1000 uA (max.)		

# 2.3. System Performance

Table 3: System Performances

Data Transfer	Mode supporting	SDA Specification Ver 3.0			
Capacity level		micro	microSDXC		
Speed level		UHS-1 (Grade-1)	UHS-1 (Grade-3)		UHS-1 (Grade-3)
Flash	Capacity	8GB 16GB 32GB		64GB	
C	Sequential Read (MB/s)	92.0	95.0	91.0	n/a
Samsung	Sequential Write (MB/s)	27.0	62.0	62.0	n/a

#### Note:

- $\succ$  All values quoted are typically at 25  ${\mathcal C}$  and nominal supply voltage.
- The performance is obtained from TestMetrix Test (@500MB).



# 2.4. System Reliability

Table 4: System Reliability

Wear-leveling Algorithms	Static and Dynamic wear-leveling algorithms		
Bad Blocks Management	Supportive		
ECC Technology	BCH ECC		
мтвғ	> 3,000,000 hours		
Endurance	NAND MLC Flash w/MLC Technology: 3K Erase counts		
Durability	10,000 inserting cycles		
Bending	>10N		
Torque	0.1N +/- 2.5 deg.		
Drop Test	1.5M free fall		
Salt Spray	Concentration: 3% NaCl/35 $^{\circ}$ C		
Waterproof	1000mm submerge for 30 minutes, IPx7 compliance		
Electrostatic Discharge (ESD)	Contact: +/- 4KV each item 5 times		
Electiostatic disclidinge (ESD)	Air: +/- 8KV 5 times		
X-Ray Exposure Test	0.1 Gy of medium energy radiation (70 keV to 140keV, cumulative does per		
A-Ray Exposure rest	year) to both sides of the card.		

#### Note:

> The endurance of SSD could be estimated based on user behavior, NAND endurance cycles, and write amplification factor.

It is not guaranteed by flash vendor.

# 2.5. Tera Bytes Written

Table 4: System Reliability

Erase counts	NAND MLC Flash Cell Level : 3K P/E Cycles		
Capacity	TBW(TB)		
8GB	23		
16GB	47		
32GB	93		

<sup>&</sup>gt; Workload by Sequential Write.

The endurance of SSD could be varying based on user behavior, NAND endurance cycles, and write amplification factor. It is not guaranteed by flash vendor.



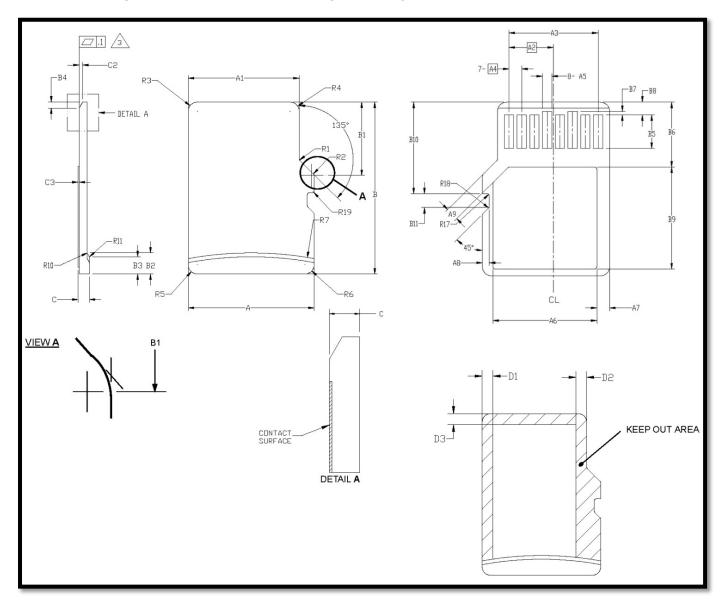
# 2.6. Physical Specifications

Refer to Table 5 and see Figure 1 for APRO MLC Micro Secure Digital Memory Card PHANES-F Series physical specifications and dimensions.

Table 5: Physical Specifications of APRO MLC Micro Secure Digital Memory Card PHANES-F Series

Length:	15.00 mm
Width:	11.00 mm
Thickness:	1.0 mm
Weight:	0.3 g / 0.01 oz

Figure 2: APRO MLC Micro Secure Digital Memory Card PHANES-F Series Dimension





	COMMON	DIMENS	IONS	
SYMBOL	MIN	NOM	MAX	NOTE
A	10.90	11.00	11.10	.,,,,,
A1	9.60	9.70	9.80	
A2	-	3.85	2	BASIC
A3	7.60	7.70	7.80	
A4	-	1.10	_	BASIC
A5	0.75	0.80	0.85	
A6	9 <del>-</del> 9	-	8.50	
A7	0.90	•	7	
A8	0.60	0.70	0.80	
A9	0.80	-		
В	14.90	15.00	15.10	
B1	6.30	6.40	6.50	
B2	1.64	1.84	2.04	
В3	1.30	1.50	1.70	
B4	0.42	0.52	0.62	
B5	2.80	2.90	3.00	
В6	5.50	1	7	
B7	0.20	0.30	0.40	
B8	1.00	1.10	1.20	
B9	-	-	9.00	
B10	7.80	7.90	8.00	
B11	1.10	1.20	1.30	
С	0.90	1.00	1.10	
C1	0.60	0.70	0.80	
C2	0.20	0.30	0.40	
C3	0.00	-	0.15	
D1	1.00		-	
D2	1.00	-	724	
D3	1.00	-	1. <del>-</del> 1	
R1	0.20	0.40	0.60	
R2	0.20	0.40	0.60	
R3	0.70	0.80	0.90	
R4	0.70	0.80	0.90	
R5	0.70	0.80	0.90	
R6	0.70	0.80	0.90	
R7	29.50	30.00	30.50	
R10	-	0.20	-	
R11	2	0.20	2	
R17	0.10	0.20	0.30	
R18	0.20	0.40	0.60	
R19	0.05	-	0.20	

## Notes:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 2. DIMENSIONS ARE IN MILLIMETERS.

COPLANARITY IS ADDITIVE TO C1 MAX THICKNESS.



## 3. Interface Description

# 3.1. Micro Secure Digital Memory Card interface

APRO MLC Micro Secure Digital Memory Card has 8 exposed contacts on one side.

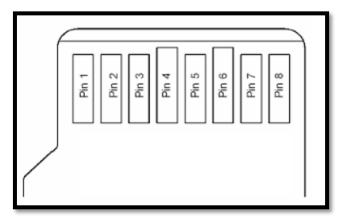


Figure 3: 8 Pins Connector

## 3.2. Pin Assignments

There are total of 8 pins in the Micro SD Connector. The pin assignments are listed in below table 6.

Pin Number	SD Mode			SPI Mode		
Pin Number	Pin Name	Type <sup>1</sup>	Description	Pin Name	Туре	Description
Pin 1	DAT2	I/O/PP	Data Line [bit2]	RSV		
Pin 2	CD / DAT3 <sup>2</sup>	I/O/PP <sup>3</sup>	Card Detect / Data Line [bit3]	CS	$I^3$	Chip Select
Pin 3	CMD	PP	Command / Response	DI	I	Data in
Pin 4	$V_{DD}$	S	Supply voltage	$V_{DD}$	S	Supply voltage
Pin 5	CLK	I	Clock	SCLK	I	Clock
Pin 6	V <sub>SS</sub>	S	Supply voltage ground	V <sub>SS</sub>	S	Supply voltage ground
Pin 7	DAT0	I/O/PP	Data Line [bit0]	DO	O/PP	Data Out
Pin 8	DAT1	I/O/PP	Data Line [bit1]	RSV		

Table 6 - Pin Assignments

- > S: power supply, I:input; O:output using push-pull drivers; PP:I/O using push-pull drivers.
- > The extended DAT lines (DAT1-DAT3) are input on power up. They start to operate as DAT lines after SET\_BUS\_WIDTH command. The Host shall keep its own DAT1-DAT3 lines in input mode, as well, while they are not used. It is defined so, in order to keep compatibility to Multi-Media Cards.
- At power up this line has a 50KOhm pull up enabled in the card. This resistor serves two functions Card detection and Mode Selection. For Mode Selection, the host can drive the line high or let it be pulled high to select SD mode. If the host wants to select SPI mode it should drive the line low. For Card detection, the host detects that the line is pulled high. This pull-up should be disconnected by the user during regular data transfer period, withSET\_CLR\_CARD\_DETECT(ACMD42) command.



# Appendix A: Limited Warranty

APRO warrants your MLC Micro Secure Digital Memory Card PHANES-F Series against defects in material and workmanship for the life of the drive. The warranty is void in the case of misuse, accident, alteration, improper installation, misapplication or the result of unauthorized service or repair. The implied warranties of merchantability and fitness for a particular purpose, and all other warranties, expressed or implied, except as set forth in this warranty, shall not apply to the products delivered. In no event shall APRO be liable for any lost profits, lost savings or other incidental or consequential damages arising out of the use of, or inability to use, this product.

#### BEFORE RETURNING PRODUCT, A RETURN MATERIAL AUTHORIZATION (RMA) MUST BE OBTAINED FROM APRO.

Product shall be returned to APRO with shipping prepaid. If the product fails to conform based on customers' purchasing orders, APRO will reimburse customers for the transportation charges incurred.

#### **WARRANTY PERIOD:**

#### MLC ( Standard grade / Wide temp. grade ) 2 years / Within 3K Erasing Counts

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